

ABSTRACT

An optical device package includes a substrate having a top portion with an a recess for receiving an optical semiconductor component and an elongated linear groove for receiving an optical fiber. The optical fiber is positioned within the groove in said substrate such that the top surface of the optical fiber is substantially at or below the upper surface of the substrate and the optical fiber is operatively aligned with the optical semiconductor component for the transfer of optical signals therebetween. A frame is hermetically sealed to the upper surface of the substrate.